ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SSOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	80	40 000	200 °C + N2	0	0
HAST	956	95 600	130 °C, 85 % RH	0	0
Pressure Pot	1192	114 432	121°, 15 PSIG	0	0
Solder DUNK	300	900	260 °C, 10 s	0	0
Solderability	150	1170	883 M2003	0	0
Temp. Cycle	3192	1 412 000	-55 °C to 150 °C	0	0

For technical questions, contact: pmostechsupport@vishay.com

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